



SN75LVPE801 8.0 Gbps SATA Express Equalizer and Redriver

1 Features

- SATA Express Support
- Selectable Equalization and De-Emphasis
- Hot Plug Capable
- Receiver Detect and OOB Support
- Multirate Operation
 - SATA: 1.5 Gbps, 3.0 Gbps, 6.0 Gbps
 - PCIe: 2.5 Gbps, 5.0 Gbps, 8.0 Gbps
- Suitable to Receive 8.0 Gbps Data Over Up to 40 Inches (1.0 Meter) of FR4 PC Board
- Compensates Up to 14-dB Loss on the Receive Side and 1.2dB Loss on the Transmit Side at 3 GHz
- Integrated Output Squelch
- Temperature range 0°C – 85°C
- Auto Low Power Feature Lowers Power by > 90%
 - < 100 mW (Active Mode, Typical)
 - < 11 mW (Auto Low Power Mode, Typical)
- Single 3.3-V Supply
- High Protection Against ESD Transient
 - HBM: 6 kV
 - CDM: 1.5 kV
- Ultra-Small Footprint: 2 mm × 2 mm WSON Package

2 Applications

- Notebooks
- Desktops
- Docking Stations
- Servers
- Workstations

3 Description

The SN75LVPE801 is a versatile single channel, SATA Express signal conditioner supporting data rates up to 8 Gbps. The device supports SATA Gen 1, 2, and 3 specifications as well as PCIe 1.0, 2.0, and 3.0. The SN75LVPE801 operates from a single 3.3-V supply and has 100-Ω line termination with self-biasing feature, making the device suitable for AC coupling. The inputs incorporate an out-of-band (OOB) detector, which automatically squelches the output when the input differential voltage falls below threshold while maintaining a stable common-mode voltage. The device is also designed to handle spread spectrum clocking (SSC) transmission per SATA standard.

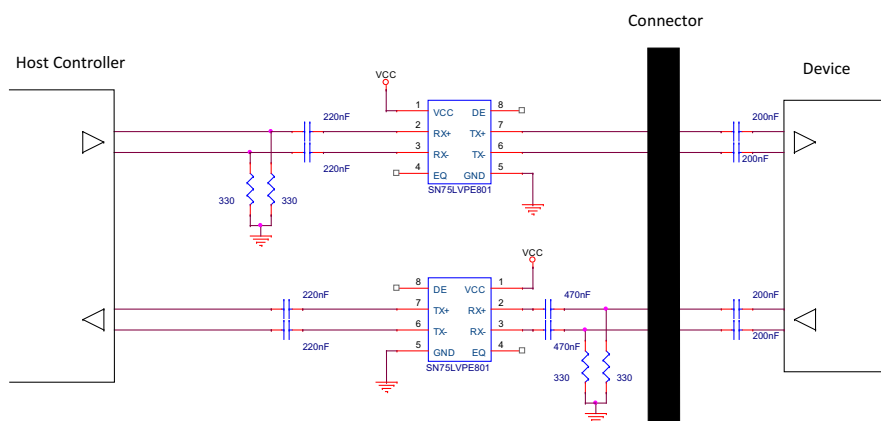
The SN75LVPE801 handles interconnect losses at its input with selectable equalization settings that can be programmed to match the loss in the channel. For data rates of 8 Gbps and lower the SN75LVPE801 equalizes signals for a span of up to 50 inches of FR4 board material. For data rates of 8 Gbps the device compensates up to 40 in of FR4 material. The equalization level is controlled by the setting of the signal control pin EQ.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN75LVPE801	WSON (8)	2.00 mm × 2.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

SATA Express Reference Schematic



Copyright © 2016, Texas Instruments Incorporated



Table of Contents

1 Features	1	9.3 Feature Description	10
2 Applications	1	9.4 Device Functional Modes	13
3 Description	1	10 Applications and Implementation	14
4 Revision History	2	10.1 Application Information	14
5 Description (continued)	3	10.2 Typical SATA Applications	14
6 Pin Configuration and Functions	3	11 Power Supply Recommendations	21
7 Specifications	4	12 Layout	22
7.1 Absolute Maximum Ratings	4	12.1 Layout Guidelines	22
7.2 ESD Ratings	4	12.2 Layout Example	24
7.3 Recommended Operating Conditions	4	13 Device and Documentation Support	26
7.4 Thermal Information	4	13.1 Device Support	26
7.5 Electrical Characteristics	5	13.2 Receiving Notification of Documentation Updates	26
7.6 Timing Requirements	7	13.3 Community Resources	26
7.7 Typical Characteristics	8	13.4 Trademarks	26
8 Parameter Measurement Information	9	13.5 Electrostatic Discharge Caution	26
9 Detailed Description	10	13.6 Glossary	26
9.1 Overview	10	14 Mechanical, Packaging, and Orderable Information	26
9.2 Functional Block Diagram	10		

4 Revision History

DATE	REVISION	NOTES
September 2016	*	Initial release.

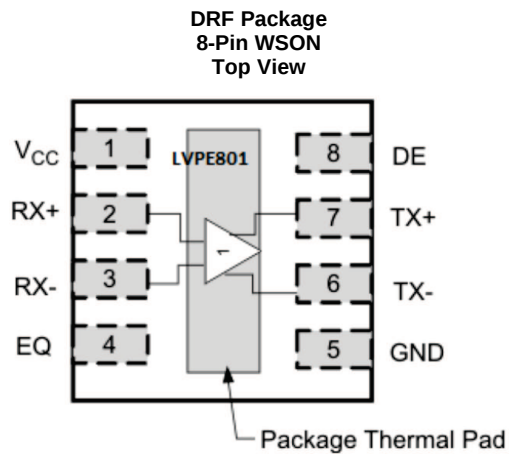
5 Description (continued)

Two de-emphasis levels can be selected on the transmit side to provide 0 dB or 1.2 dB of additional high-frequency loss compensation at the output.

The device is hot-plug capable⁽¹⁾ preventing device damage under device *hot*-insertion such as async signal plug and removal, unpowered plug and removal, powered plug and removal, or surprise plug and removal.

(1) Requires use of AC coupling capacitors at differential inputs and outputs.

6 Pin Configuration and Functions



PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
HIGH SPEED DIFFERENTIAL I/O			
RX+	2	I	Noninverting and inverting CML differential inputs. These pins are tied to an internal voltage bias by dual termination resistor circuit.
RX−	3	I	
TX+	7	O	Noninverting and inverting VML differential outputs. These pins are tied to an internal voltage bias by dual termination resistor circuit.
TX−	6	O	
CONTROL PINS			
EQ	4	I	Selects equalization settings per Table 1 . Internally tied to GND.
DE	8	I	Selects de-emphasis settings per Table 1 . Internally tied to GND.
POWER			
V _{CC}	1	P	Positive supply must be 3.3 V ±10%
GND	5	G	Supply ground

(1) G = Ground, I = Input, O = Output, P = Power

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Supply voltage, V_{CC} ⁽²⁾		−0.5	4	V
Voltage	Differential I/O	−0.5	4	V
	Control I/O	−0.5	$V_{CC} + 0.5$	
Storage temperature, T_{stg}		−65	150	°C

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any conditions beyond those indicated under [Recommended Operating Conditions](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to network ground pin.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±6000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

typical values for all parameters are at $V_{CC} = 3.3$ V and $T_A = 25^\circ\text{C}$; all temperature limits are specified by design

		MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage	3	3.3	3.6	V
	Coupling capacitor	75	100	200	nF
T_A	Operating free-air temperature	0		85	°C

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN75LVPE801	UNIT
		DRF (WSON)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	97.8	°C/W
$R_{\theta Jtop}$	Junction-to-case (top) thermal resistance	81.9	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	65.6	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	1.3	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	65.6	°C/W
$R_{\theta Jcbot}$	Junction-to-case (bottom) thermal resistance	19.1	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Electrical Characteristics

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DEVICE PARAMETERS						
ICC _{Max-s}	Active mode supply current	EQ/DE = NC, K28.5 pattern at 8 Gbps, V _{ID} = 700 mV _{pp}	29	40		mA
I _{CCPS}	Auto power save mode I _{CC}	When auto low power conditions are met	3.3	5.9		mA
	Maximum data rate			8		Gbps
OOB						
V _{OOB}	Input OOB threshold	F = 750 MHz	50	70	90	mV _{pp}
D _{VdiffOOB}	OOB differential delta			25		mV
D _{VCMOOB}	OOB common-mode delta			50		mV
CONTROL LOGIC						
V _{IH}	High-level input voltage	For all control pins	1.4			V
V _{IL}	Low-level input voltage			0.5		V
V _{INHYS}	Input hysteresis		115			mV
I _{IH}	High-level input current	V _{IH} = V _{CC} (DE/EQ)		20		μA
I _{IL}	Low-level input current	V _{IL} = 0V (DE/EQ)	10			μA
RECEIVER AC/DC						
Z _{DIFFRX}	Differential input impedance		85	100	115	Ω
Z _{SERX}	Single-ended input impedance		40			Ω
V _{CMRX}	Common-mode voltage			1.7		V
RL _{DiffRX}	Differential mode return loss (RL)	f = 150 MHz to 300 MHz	20	26		dB
		f = 300 MHz to 600 MHz	18	22		
		f = 600 MHz to 1.2 GHz	14	17		
		f = 1.2 GHz to 2.4 GHz	10	12		
		f = 2.4 GHz to 3 GHz	8	12		
		f = 3 GHz to 5 GHz	6	11		
RX _{DiffRLSlope}	Differential mode RL slope	f = 300 MHz to 6 GHz (see Figure 6)		−13		dB/dec
RL _{CMRX}	Common-mode return loss	f = 150 MHz to 300 MHz	8	9		dB
		f = 300 MHz to 600 MHz	14	17		
		f = 600 MHz to 1.2 GHz	12	18		
		f = 1.2 GHz to 2.4 GHz	8	10		
		f = 2.4 GHz to 3 GHz	6	8		
		f = 3 GHz to 5 GHz	6	8.5		
V _{diffRX}	Differential input voltage PP	f = 1.5 GHz and 3 GHz	120		1600	mV _{pp}
IB _{RX}	Impedance balance	f = 150 MHz to 300 MHz	30	41		dB
		f = 300 MHz to 600 MHz	34	41		
		f = 600 MHz to 1.2 GHz	24	33		
		f = 1.2 GHz to 2.4 GHz	14	24		
		f = 2.4 GHz to 3 GHz	12	26		
		f = 3 GHz to 5 GHz	6	18		
		f = 5 GHz to 6.5 GHz	5	18		
TRANSMITTER AC/DC						
Z _{diffTX}	Pair differential impedance		85	100	122	Ω
Z _{SETX}	Single-ended input impedance		40			Ω
V _{TXtrans}	Sequencing transient voltage	Transient voltages on the serial data bus during power sequencing (lab load)	−1.2	0.3	1.2	V

Electrical Characteristics (continued)

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
RL _{DiffTX}	Differential mode return loss	f = 150 MHz to 300 MHz	14	22		dB
		f = 300 MHz to 600 MHz	12	21		
		f = 600 MHz to 1.2 GHz	11	18		
		f = 1.2 GHz to 2.4 GHz	10	14		
		f = 2.4 GHz to 3 GHz	10	14		
		f = 3 GHz to 5 GHz	8	14		
TX _{DiffRLSlope}	Differential mode RL slope	f = 300 MHz to 3 GHz (see Figure 6)		–13		dB/dec
RL _{CMTX}	Common-mode return loss	f = 150 MHz to 300 MHz	10	20		dB
		f = 300 MHz to 600 MHz	9	16		
		f = 600 MHz to 1.2 GHz	8	13.5		
		f = 1.2 GHz to 2.4 GHz	6	8.5		
		f = 2.4 GHz to 3 GHz	5	8		
		f = 3 GHz to 5 GHz	4	7		
IB _{TX}	Impedance balance	f = 150 MHz to 300 MHz	34	38		dB
		f = 300 MHz to 600 MHz	32	38		
		f = 600 MHz to 1.2 GHz	24	33		
		f = 1.2 GHz to 2.4 GHz	18	25		
		f = 2.4 GHz to 3 GHz	18	25		
		f = 3 GHz to 5 GHz	12	21		
		f = 5 GHz to 6.5 GHz	8	21		
Diff _{VppTX}	Differential output voltage swing	f = 3 GHz (under no interconnect loss)	400	650	900	mV _{pp}
VCM _{AC_TX}	TX AC CM voltage	At 1.5 GHz		15	50	mV _{pp}
		At 3 GHz		10	26	dBmV (rms)
		At 6 GHz		12	30	dBmV (rms)
VCM _{TX}	Common-mode voltage			1.70		V
TRANSMITTER JITTER 3 Gbps						
DJ _{TX}	Residual deterministic jitter	VID = 500 mV _{pp} , UI = 333 ps, K28.5 control character, see Figure 7		0.12	0.19	UI _{pp}
RJ _{TX}	Random jitter	VID = 500 mV _{pp} , UI = 333 ps, K28.7 control character, see Figure 7		1	2	ps-rms
TRANSMITTER JITTER 6 Gbps						
DJ _{TX}	Residual deterministic jitter	VID = 500 mV _{pp} , UI = 167 ps, K28.5 control character, see Figure 7		0.12	0.34	UI _{pp}
RJ _{TX}	Random jitter	VID = 500 mV _{pp} , UI = 167 ps, K28.7 control character, see Figure 7		0.95	2	ps-rms
TRANSMITTER JITTER 8 Gbps						
DJ _{TX}	Residual deterministic jitter	VID = 500 mV _{pp} , UI = 125 ps, K28.5 control character, see Figure 7	4.7	5.76	8.7	(ps) (DD)
RJ _{TX}	Random jitter	VID = 500 mV _{pp} , UI = 125 ps, K28.5 control character, see Figure 7	0.93	0.94	0.95	ps-rms
DJ _{TX}	Residual deterministic jitter	VID = 500 mV _{pp} , UI = 125 ps, K28.7 control character, see Figure 7	0.8	1.24	2.7	(ps) (DD)
RJ _{TX}	Random jitter	VID = 500 mV _{pp} , UI = 125 ps, K28.7 control character, see Figure 7	0.9	0.92	0.93	ps-rms

7.6 Timing Requirements

			MIN	TYP	MAX	UNIT
DEVICE PARAMETERS						
t_{PDelay}	Propagation delay	Measured using K28.5 pattern (see Figure 1)		275	350	ps
AutoLP _{ENTRY}	Auto low power entry time	Electrical idle at input (see Figure 3)		11		μs
AutoLP _{EXIT}	Auto low power exit time	After first signal activity (see Figure 3)		33	50	ns
OOB						
t_{OOB1}	OOB mode enter	See Figure 2		1	5	ns
t_{OOB2}	OOB mode exit	See Figure 2		1	5	ns
RECEIVER AC/DC						
$t_{20-80RX}$	Rise and fall time	Rise times and fall times measured between 20% and 80% of the signal. SATA 8 Gbps speed measured 1" from device pin.	62		75	ps
t_{skewRX}	Differential skew	Difference between the single-ended mid-point of the RX+ signal rising and falling edge, and the single-ended mid-point of the RX– signal falling and rising edge.			30	ps
TRANSMITTER AC/DC						
$t_{20-80TX}$	Rise and fall time	Rise times and fall times measured between 20% and 80% of the signal. At 8 Gbps under no load conditions measured at the pin.	44	58	85	ps
t_{skewTX}	Differential skew	Difference between the single-ended mid-point of the TX+ signal rising edge and falling edge, and the single-ended mid-point of the TX– signal falling edge and rising edge, D1, D0 = V _{CC}		2	15	ps
$t_{xR/Fimb}$	TX rise and fall imbalance	At 8 Gbps		6%	20%	
$t_{xAmplmb}$	TX amplitude imbalance			1%	10%	
TRANSMITTER JITTER						
	Rise and Fall time		46.5%	47.5%	48.3%	
	Rise and Fall mismatch			1.5%	3%	

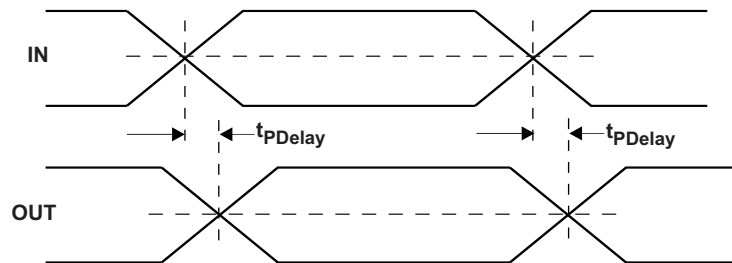


Figure 1. Propagation Delay Timing Diagram

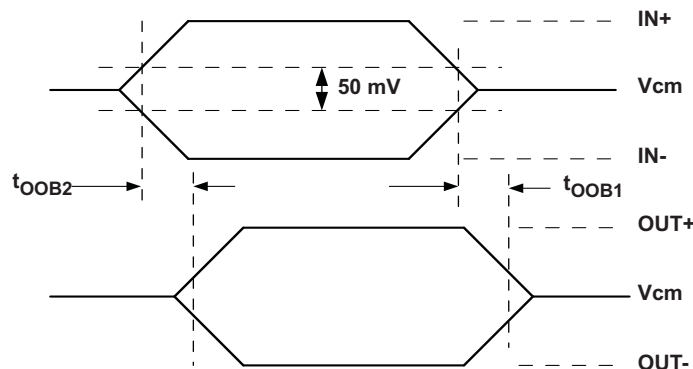


Figure 2. OOB Enter and Exit Timing

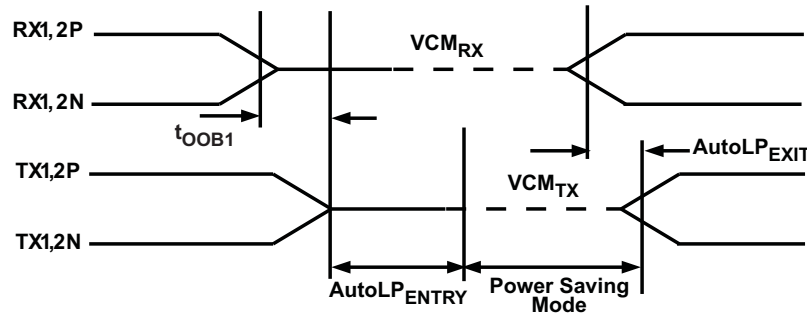
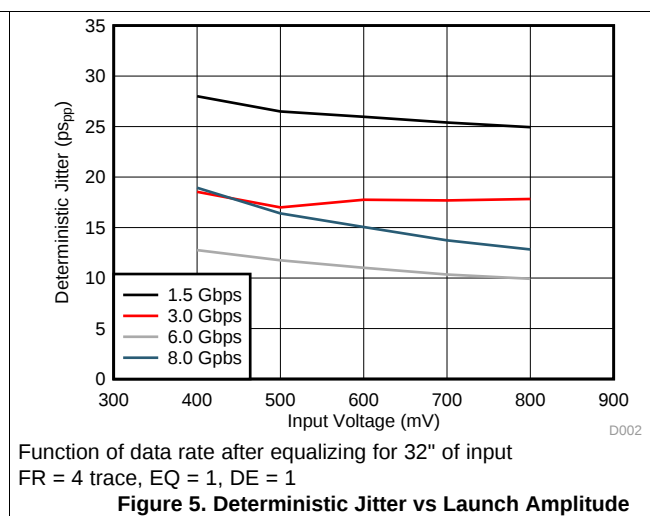
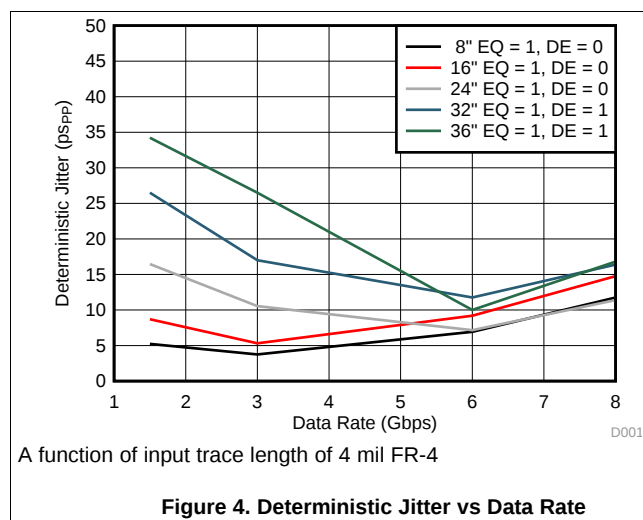


Figure 3. Auto Low Power Mode Entry and Exit Timing

7.7 Typical Characteristics



8 Parameter Measurement Information

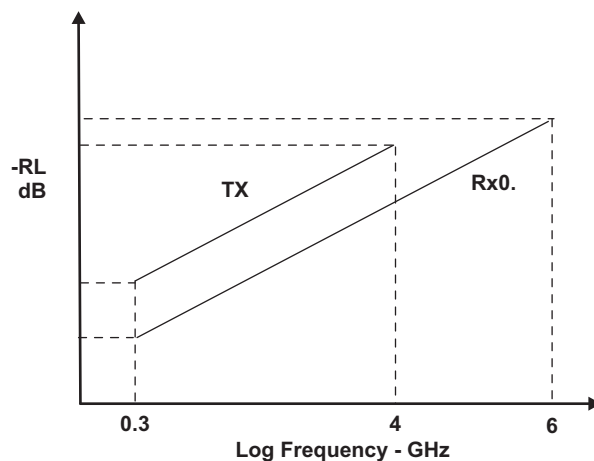


Figure 6. TX, RX Differential Return Loss Limits

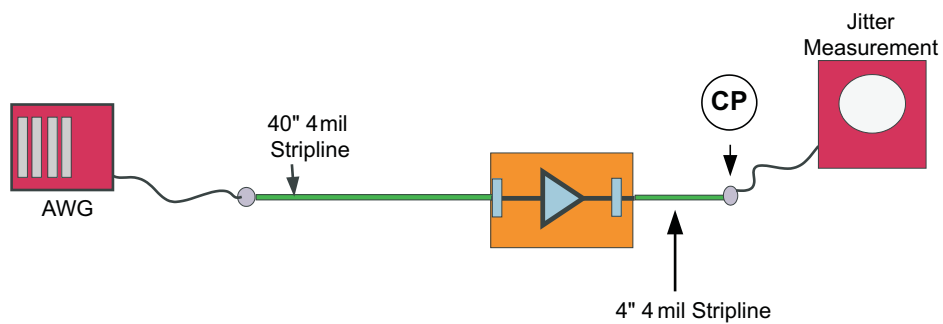


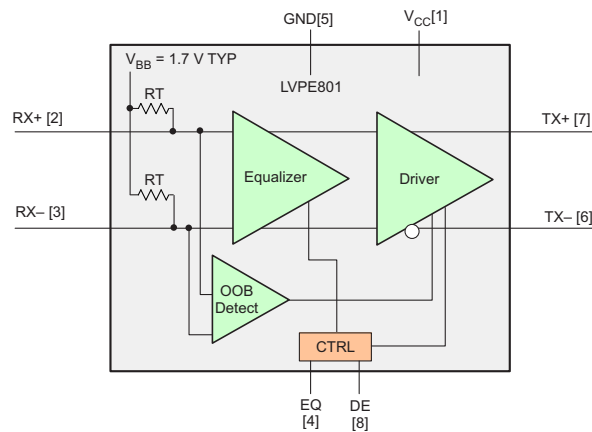
Figure 7. Jitter Measurement Test Condition

9 Detailed Description

9.1 Overview

The SN75LVPE801 is a single channel equalizer and redriver. The device operates over a wide range of signaling rates, supporting operation from DC to 8 Gbps. The wide operating range supports SATA Gen 1,2,3 (1.5 Gbps, 3.0 Gbps, and 6.0 Gbps respectively) as well as PCI Express 1.0, 2.0, 3.0 (2.5 Gbps, 5.0 Gbps, and 8.0 Gbps). The device also supports SATA Express (SATA 3.2) which is a form factor specification that allows for SATA and PCI Express signaling over a single connector.

9.2 Functional Block Diagram



Copyright © 2016, Texas Instruments Incorporated

9.3 Feature Description

9.3.1 SATA Express

SATA Express (sometimes SATAe) is an electro-mechanical standard that supports both SATA and PCI Express storage devices. SATAe is standardized in the SATA 3.2 standard. The standard is concerned with providing a smooth transition from SATA to PCIe storage devices. The standard provides for standardized cables and connectors, and muxes the PCIe and SATA lanes at the host side so that either SATA compliant or PCIe compliant devices may operate with a host.

SATAe provides support for SATA1, SATA2 and SATA3 devices (operating from 1.5 Gbps to 6.0 Gbps), as well as PCIe1, PCIe2 and PCIe3 devices (operating from 2.5 Gbps to 8.0 Gbps).

The SN75LVPE801 provides for equalization and re-drive of a single channel input signal complying with any of the SATA or PCIe standards available with SATAe.

The SATAe standard provides for a mechanism for a host to recognize and detect whether a SATA or PCIe device is plugged into the host. See the [Typical SATA Applications](#) section for the details of the SATA Express Interface Detect operation.

9.3.2 Receiver Termination

The receiver has integrated terminations to an internal bias voltage. The receiver differential input impedance is nominally 100 Ω, with a ±15% variation.

For PCI Express compatibility it is necessary to include 330 Ω pull-down resistors between the connector and the AC capacitors, refer to [Figure 24](#) for more information.

9.3.3 Receiver Internal Bias

The SN75LVPE801 receiver is internally biased to 1.7 V, providing support for AC coupled inputs.

Feature Description (continued)

9.3.4 Receiver Equalization

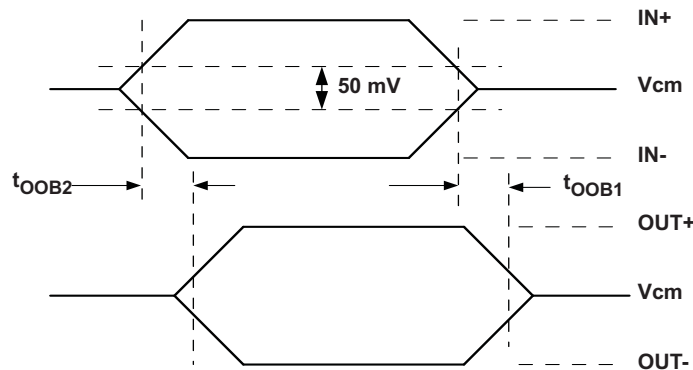
The SN75LVPE801 incorporates programmable equalization. The EQ input controls the level of equalization that is used to open the eye of the received input signal. If the EQ input is left open, or pulled LO, 8 dB (at 4 GHz) of equalization is applied. When the EQ input is HIGH, the equalization is set to 16 dB (again at 4 GHz). [Table 1](#) shows the equalization values discussed.

Table 1. EQ and DE Settings

EQ	EQUALIZATION dB (at 8 Gbps)	DE	DE-EMPHASIS
0 (default)	8	0 (default)	0
1	16	1	-1.2

9.3.5 OOB/Squelch

The SN75LVPE801 receiver incorporates an Out-Of-Band (OOB) detection circuit in addition to the main signal chain receiver. The OOB detector continuously monitors the differential input signal to the device. The OOB detector has a 50-mVpp entry threshold. If the differential signal at the receiver input is less than the OOB entry threshold, the device transmitter transitions to squelch. The SN75LVPE801 enters squelch within 5 ns of the input signal falling below the OOB entry threshold. The SN75LVPE801 continues to monitor the input signal while in squelch. While in squelch, if the OOB detector determines that the input signal now exceeds the 90 mVpp exit threshold, the SN75LVPE801 exits squelch within 5 ns. See [Figure 8](#).



**Figure 8. OOB Enter and Exit Timing
Receiver Input Termination is Disabled**

When the SN75LVPE801 enters squelch state the transmitter output is squelched. The transmitter non-inverting (TX+) output and the transmitter inverting output (TX-) are both driven to the transmitter nominal common mode voltage which is 1.7 V.

9.3.6 Auto Low Power

The SN75LVPE801 also includes an Auto Low Power Mode (ALP). ALP is entered when the differential input signal has been less than 50 mV for > 10 μ s. The device enters and exits Low Power Mode by actively monitoring the input signal level. In this state the device selectively shuts off internal circuitry to lower power by > 90% of its normal operating power. While in ALP mode the device continues to actively monitor input signal levels. When the input signal exceeds the OOB exit threshold level, the device reverts to the active state. Exit time from Auto Low Power Mode is < 50 ns (max). See [Figure 9](#).

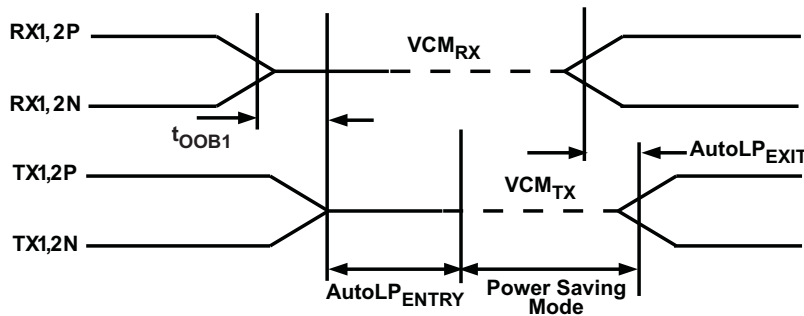


Figure 9. Auto Low Power Mode Entry and Exit Timing

9.3.7 Transmitter Output Signal

The SN75LVPE801 differential output signal is 650 mVpp when de-emphasis is disabled (DE input is open or pulled low).

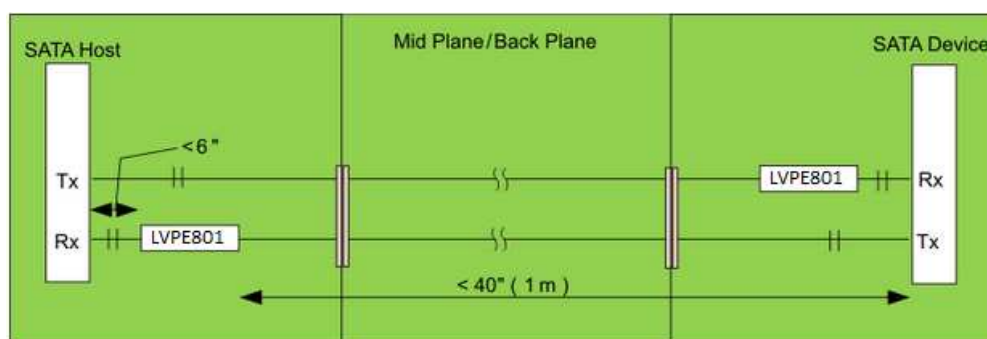
9.3.8 Transmitter Common Mode

The SN75LVPE801 transmitter common mode output is set to 1.7 V.

9.3.9 De-Emphasis

The SN75LVPE801 transmitter incorporates programmable de-emphasis to provide signal conditioning to offset the anticipated channel losses based on expected use cases for the device. Figure 10 shows an example of a SATA host communicating with a SATA device through a backplane. In such a use case, an SN75LVPE801 would be located at the end of the interconnect channels (i.e. at the device end for the host TX channel, and at the host end for the host RX channel). These locations are selected based on the signal conditioning that is incorporated into the SN75LVPE801. The SN75LVPE801 provides up to 16 dB of equalization, while supporting up to 1.2 dB of de-emphasis. The optimum location would therefore be at the end of the interconnect, allowing the receiver equalization to address the majority of the channel loss, while the de-emphasis would be employed to overcome the much shorter interconnect length.

The DE input controls the amount of de-emphasis that is applied at the transmitter output. The de-emphasis selections are shown in Table 1. When DE is left open, or pulled low, de-emphasis shall be off. When DE is pulled HIGH, 1.2 dB of de-emphasis is used at the transmitter output.



Note:

Trace lengths are suggested values based on TI HSPICE simulations (done over programmable limits of input EQ) to meet SATA loss and jitter spec.

Actual trace length supported by the LVPE801 may be more or less than suggested values and will depend on board layout, trace widths and number of connectors used in the high speed signal path.

Figure 10. Trace Length Example

9.3.10 Transmitter Termination

The SN75LVPE801 transmitter includes integrated terminations. The receiver differential output impedance is nominally 100 Ω , with a $\leq 22\%$ variation.

9.4 Device Functional Modes

9.4.1 Active

Active mode is the normal operating mode. When power is applied to the device, and the differential input signal to the receiver is greater than 90 mV_{pp}, the device is in active mode and meets all the specifications in the data sheet.

9.4.2 Squelch

When the device is powered, and the differential input signal to the receiver is less than 50 mV_{pp}, the device is in squelch mode. In squelch mode the transmitter outputs are both set to VCM_{TX} or 1.7 V.

9.4.3 Auto Low Power

When the device is powered and the differential input signal to the receiver has been less than 50 mV_{pp} for greater than 10 ns, the device transitions to Auto Low Power (ALP) mode. In ALP, the transmitter outputs are both set to VCM_{TX}. In addition, while in ALP, the device shuts off internal circuitry to lower power to less than 10% of the power in the Active mode.

10 Applications and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

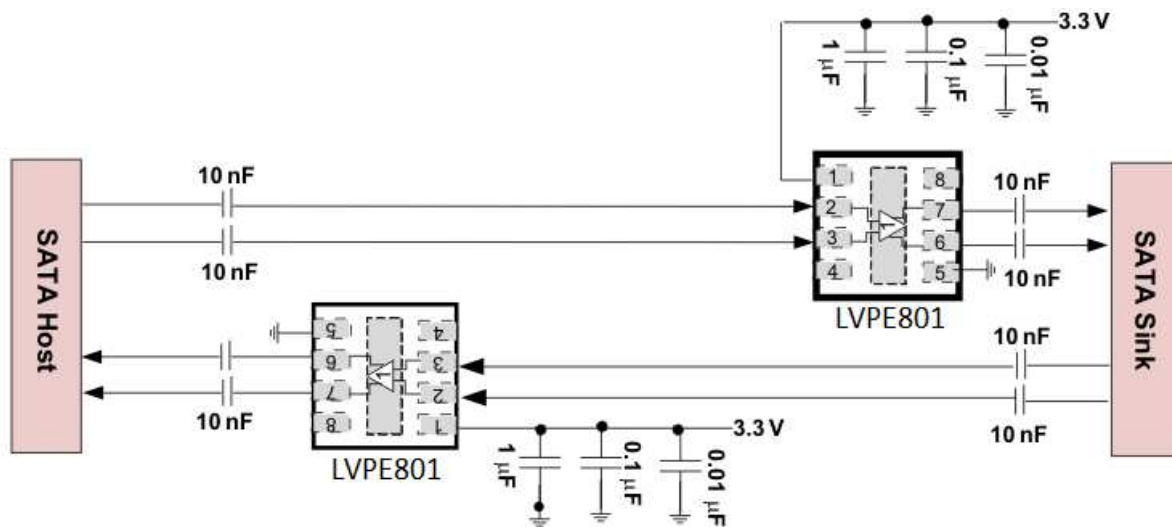
10.1 Application Information

The SN75LVPE801 can be used for SATA applications as well as SATA Express applications. The device supports SATA Gen1, Gen2, and Gen3 applications with data rates from 1.5 to 8 Gbps. The built-in equalization circuits provide up to 16 dB of equalization at 4 GHz. This equalization can support SATA GEN2 (3 Gbps) applications over up to 50 inches of FR-4 material. The same 16 dB equalizer is suited to SATA Gen3 (8 Gbps) applications up to 40 inches of FR4.

In addition to SATA applications, the SN75LVPE801 can support SATA Express applications. SATA Express provides a standardized interface to support both SATA (Gen1, Gen2, and Gen3) and PCI Express (PCIe 1.0, 2.0 and 3.0).

All applications of the SN75LVPE801 share some common applications issues. For example, power supply filtering, board layout, and equalization performance with varying interconnect losses. Other applications issues are specific, such as implementing receiver detection for SATA Express applications. The Typical Application examples demonstrate common implementations of the SN75LVPE801 supporting SATA, as well as SATA Express applications.

10.2 Typical SATA Applications



Copyright © 2016, Texas Instruments Incorporated

- (1) Place supply caps close to the device pin
- (2) EQ and DE selection at 8 dB and 0 dB respectively
- (3) Actual EQ and DE settings depend on the device placement relative to the host and SATA connector

Figure 11. Typical Device Implementation

Typical SATA Applications (continued)

10.2.1 Design Requirements

DESIGN PARAMETERS	VALUE
SATA Signaling Rate	1.5 - 6.0 Gbps
AC Coupling Capacitance	10 nF
Interconnect Characteristic Impedance	100 Ohms
Interconnect Length	Up to 50" FR4 for SATA Gen2 Up to 40" FR4 for SATA Gen3
Termination Resistance	100 Ohms differential integrated into TX and RX

10.2.2 Detailed Design Procedure

Figure 11 shows a typical SATA Application. The SATA host, which may be a notebook or desktop, communicates with a SATA sink, which could be a SSD mass storage device. The SATA host and sink communicate over a backplane differential pair, or a SATA cable. When using the SN75LVPE801 as an equalizer/redriver, the designer would optimally place the SN75LVPE801 close to the end of the interconnect. The SN75LVPE801 provides up to 16 dB of equalization, and up to 1.2 dB of de-emphasis. Placing the SN75LVPE801 close to the end of the interconnect allows the device equalizer to address the majority of the high frequency losses introduced in the channel.

Ensure that the channel loss for the interconnect material and length is matched reasonably well to the selectable equalization and de-emphasis settings available on the SN75LVPE801. The table above provides an estimate of the amount of FR4 material that could be used as a function of the signal rate. In any case, channel modeling would be prudent to ensure that the SATA host, interconnect, SATA equalizer/re-driver, and SATA Sink can establish and maintain a low BER link.

The AC coupling capacitors of 10 nF are chosen to comply with the SATA standard (< 12 nF)

Often a designer may not be sure whether a signal conditioning device like the SN75LVPE801 is needed in their specific application. The SN75LVPE801 allows the user to take the guess work of using a signal conditioning device in a SATA link. With the SN75LVPE801 the designer has the option to use or remove the device based on signal conditioning needs. **Figure 12** shows guidelines that could be used to allow in situ testing when a board is available. The designer would start with 0 Ω resistors in place to determine if the eye quality at the end of the link is satisfactory. If the eye opening is not sufficient, the 0 Ω resistors could be replaced with the SN75LVPE801.

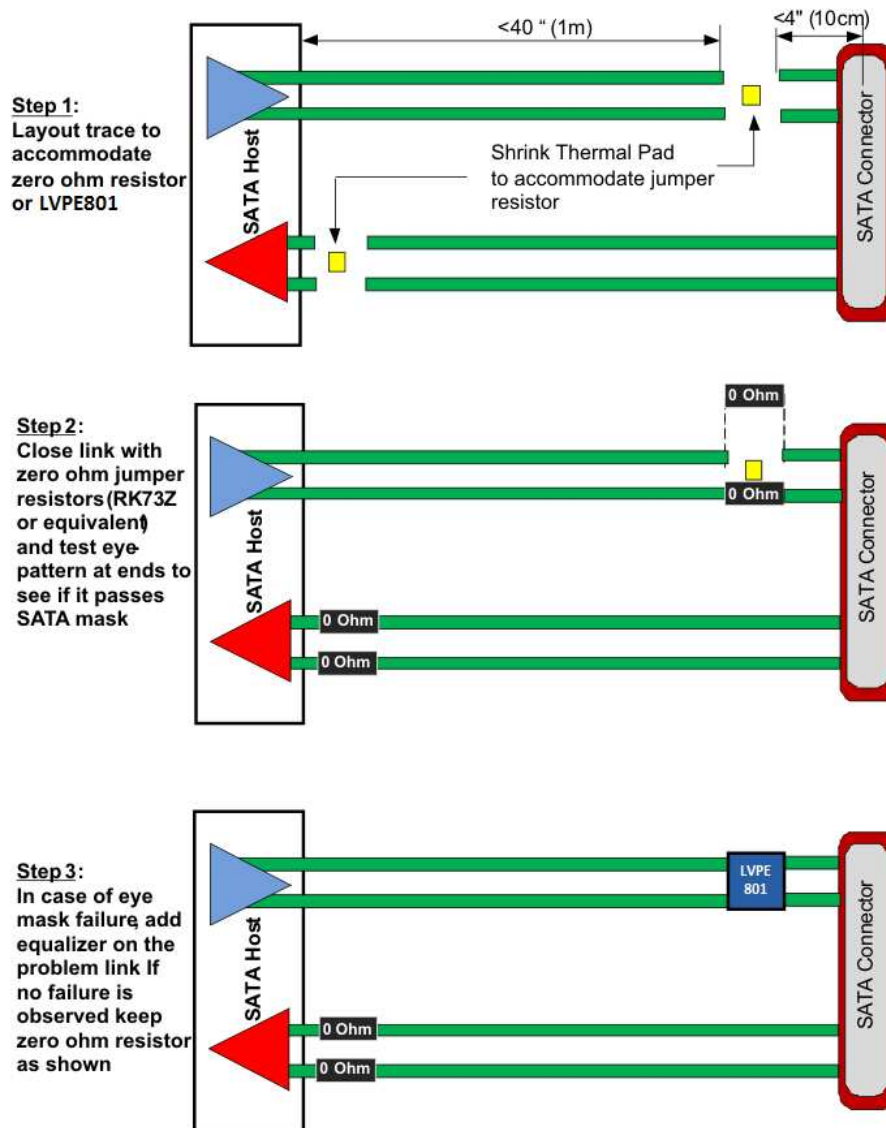


Figure 12. Implementation Guideline

To demonstrate the effectiveness of the SN75LVPE801 signal conditioning for varied configurations that may be encountered, [Figure 13](#) is used as a reference. A Gen3, 6 Gbps SATA host communicates with a sink located at point B. The host and sink are separated by “X+Y” inches, where X represents the distance between the host and the SN75LVPE801, while Y represents the distance between the SN75LVPE801 and the sink. The [Application Curves](#) are for a 6-Gbps K28.5 pattern, with $V_{CC} = 3.3\text{ V}$ and at an ambient temperature of 25°C.

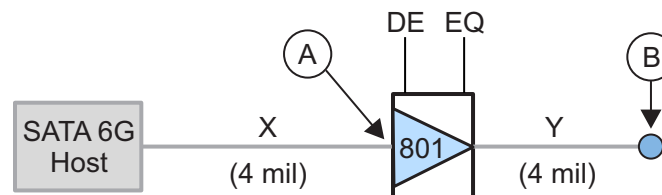


Figure 13. Test Points

10.2.3 Application Curves

All graphs at 6 Gbps

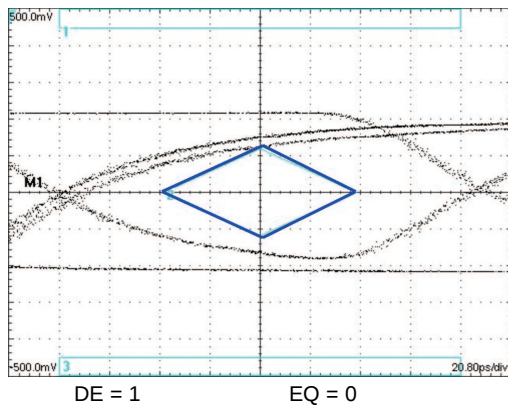


Figure 14. Eye Pattern at A → X = 8"; Y = 2"

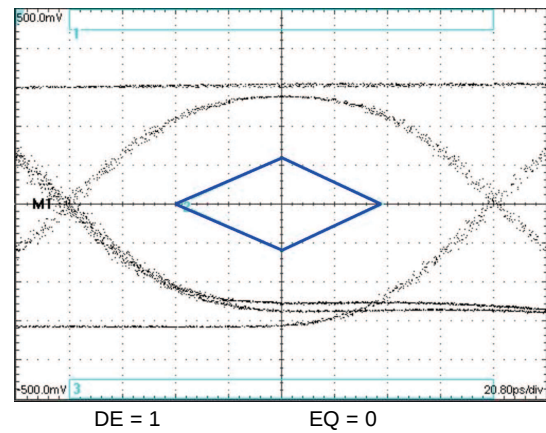


Figure 15. Eye Pattern at B → X = 8"; Y = 2"

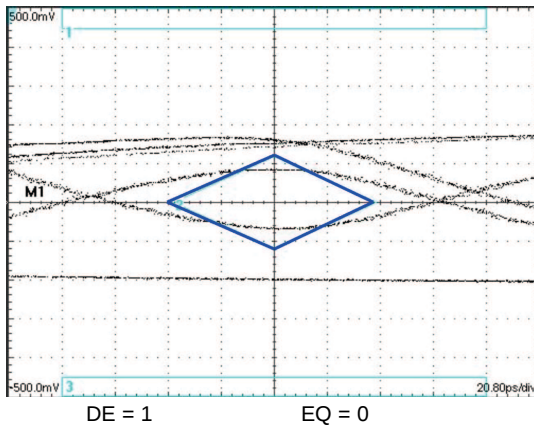


Figure 16. Eye Pattern at A → X = 16"; Y = 2"

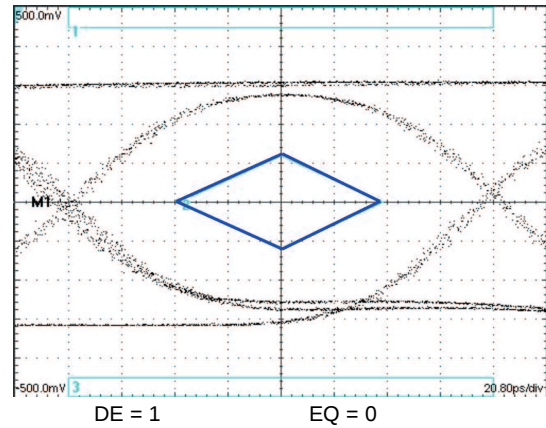


Figure 17. Eye Pattern at B → X = 16"; Y = 2"

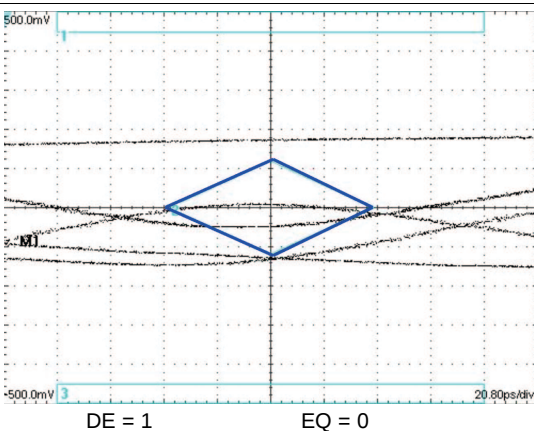


Figure 18. Eye Pattern at A → X = 24"; Y = 2"

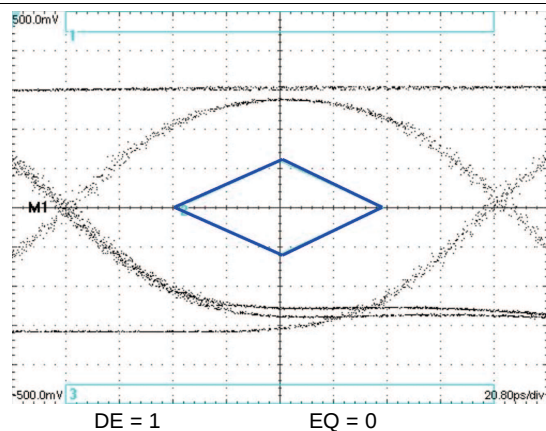


Figure 19. Eye Pattern at B → X = 24"; Y = 2"

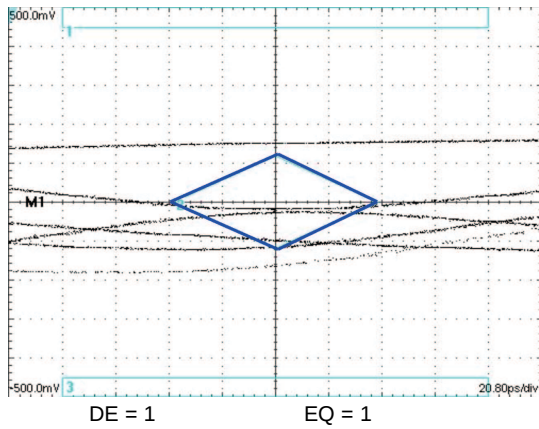


Figure 20. Eye Pattern at A → X = 32"; Y = 2"

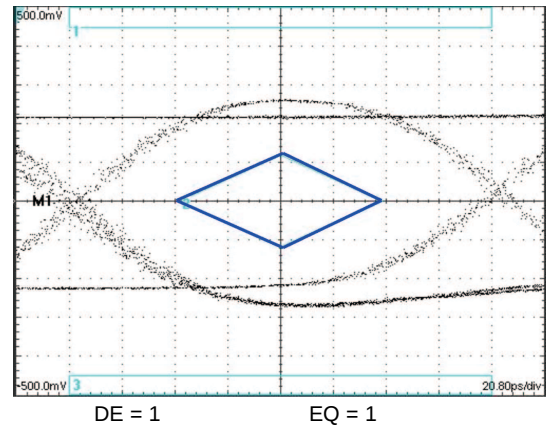


Figure 21. Eye Pattern at B → X = 32"; Y = 2"

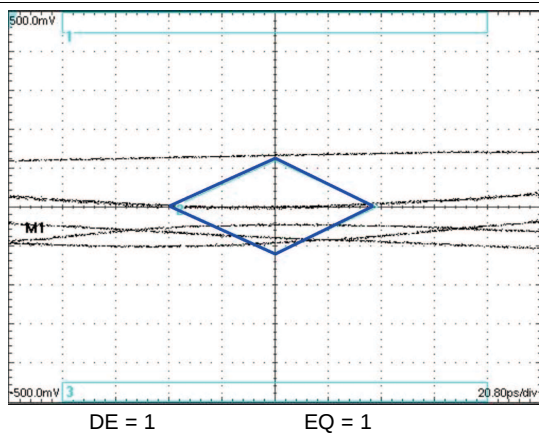


Figure 22. Eye Pattern at A → X = 40"; Y = 2"

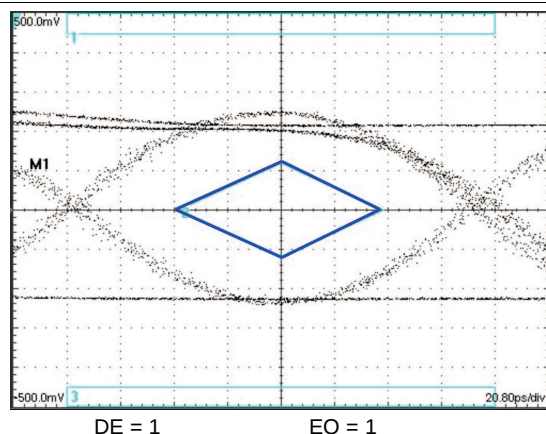
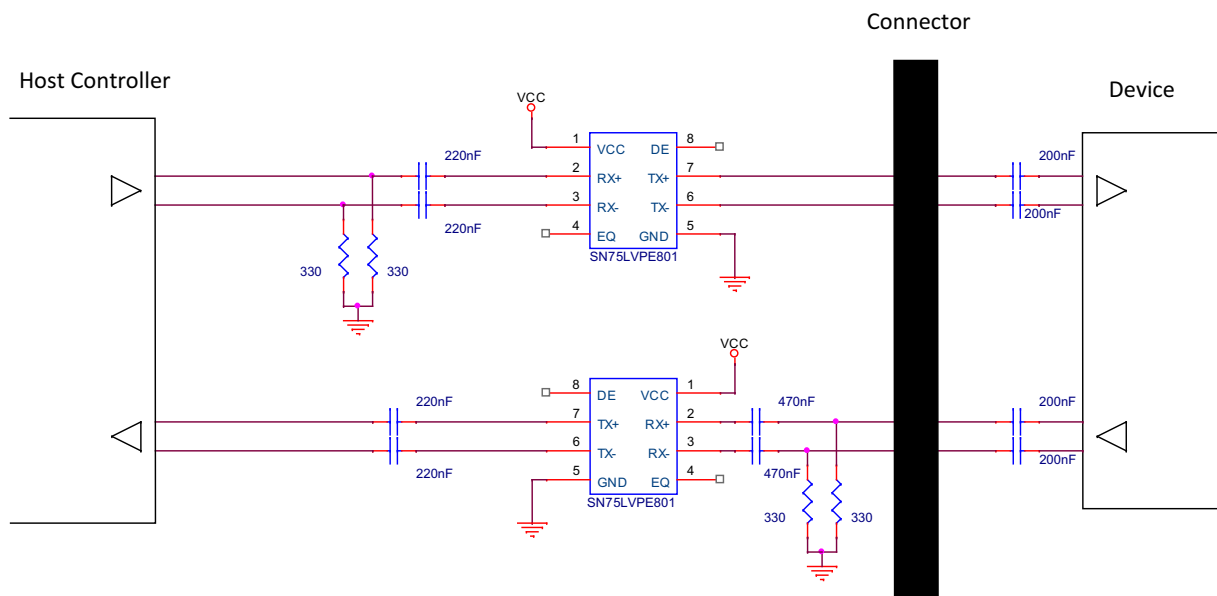


Figure 23. Eye Pattern at B → X = 40"; Y = 2"

10.2.4 SATA Express Applications



Copyright © 2016, Texas Instruments Incorporated

Figure 24. SN75LVPE801 SATA Express Reference Schematic
EQ: 8 dB when Floated, DE: 0 dB when Floated

10.2.4.1 Design Requirements

DESIGN PARAMETERS	VALUE
SATA Express Signaling Rate	1.5 - 8.0 Gbps
AC Coupling Capacitance	200 - 220 nF
Interconnect Characteristic Impedance	100 Ω
Interconnect Length	Up to 50" FR4 for SATA Gen2 Up to 40" FR4 for SATA Gen3
Receiver pull-down terminations	330 Ω
Termination Resistance	100 Ohms differential integrated into TX and RX

10.2.4.2 Detailed Design Procedure

Figure 24 is a reference schematic of a SATAe implementation using the SN75LVPE801. With a SATAe design, both SATA and PCI Express must be supported. SATAe supports both cabled and direct connections. Using a cabled application as an example, the SATAe power connector includes an Interface Detect (IFDet, power connector pin P4) signal that indicates whether a SATA client or a PCIe client is connected.

When the SATAe host determines that a PCIe client is connected, the SATAe host performs receiver detection. Receiver detection determines the presence of a client by detecting the load impedance. The transmitter performs a common mode voltage shift, and measures the rate at which the voltage at the transmitter output changes. The rate of change indicates if a client is present (fast charging when a low impedance load is present, or slow charging when the load is open or high impedance). With the implementation in Figure 24, 330- Ω pulldowns have been inserted between the host and the SN75LVPE801. The pulldown resistors indicate to the host that a client is present. While an actual client would be expected to have an active load of 50 Ω single ended, the 330 Ω is chosen here to meet two requirements. The 330 Ω is low enough to force the SATAe host to decide that a receiver is present, while also high enough to only marginally affect the load when the SN75LVPE801 is active, and presenting a 50- Ω load. With the 50 Ω and 330 Ω are both present, the parallel combination of 43 Ω is satisfactory for most applications.

Assuming that the SATAe host has detected (via IFDet) that a SATA client is present, the SATAe host communicates with the client via the SN75LVPE801. The SATA standard does not have a receiver detection mode as is present in PCIe. A SATA host does use OOB signaling to communicate identification information. The SN75LVPE801 incorporates an OOB detector in order to support OOB signaling through the device. The OOB detector drives a squelch circuit on the SN75LVPE801 output transmitter. (See [OOB/Squelch](#) for more details on the OOB/Squelch circuitry.)

Returning again to Figure 24, we see 200-nF AC coupling capacitors on the device or client side of the interface. These capacitors allow interfacing to both SATA and PCIe clients. In the case of a PCIe client, the 200 nF is within the acceptable range for all PCIe devices. When a SATA client is present, the 200 nF capacitor has little effect on the overall link, as it appears in series with the 12-nF (max) AC coupling capacitor incorporated into the SATA client. The 200 nF in series with the 12 nF presents an effective capacitance of 11.3 nF, as expected less than the 12-nF maximum permitted.

The physical placement of the resistors on the high-speed transmission lines can be made as not to create a stub on the transmission line by using resistors with the 0201 package size, an example is provided in Figure 25.

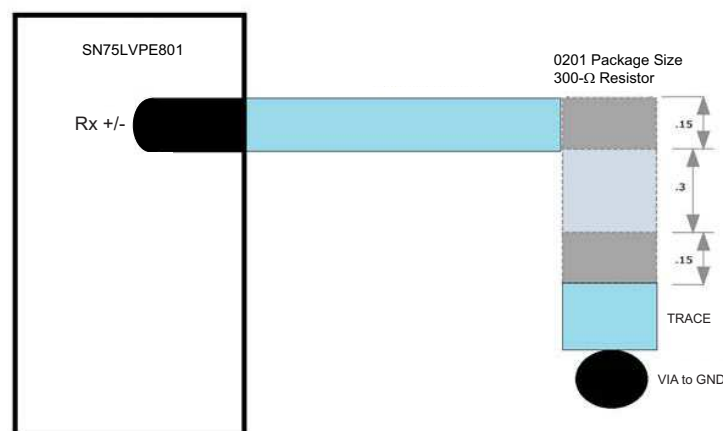


Figure 25. Resistor Placement to Avoid Stub (All Dimensions in mm)

10.2.4.3 Application Curve

Eye-diagrams were taken on the SN75LVPE801 configured as in Figure 24 above. Testing was performed at a PCIe 3.0 speed of 8Gbps.

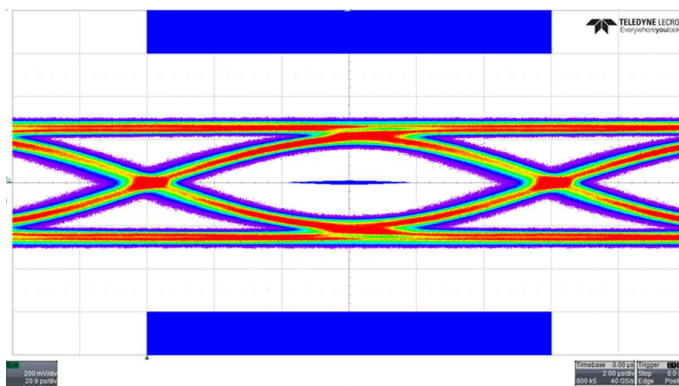
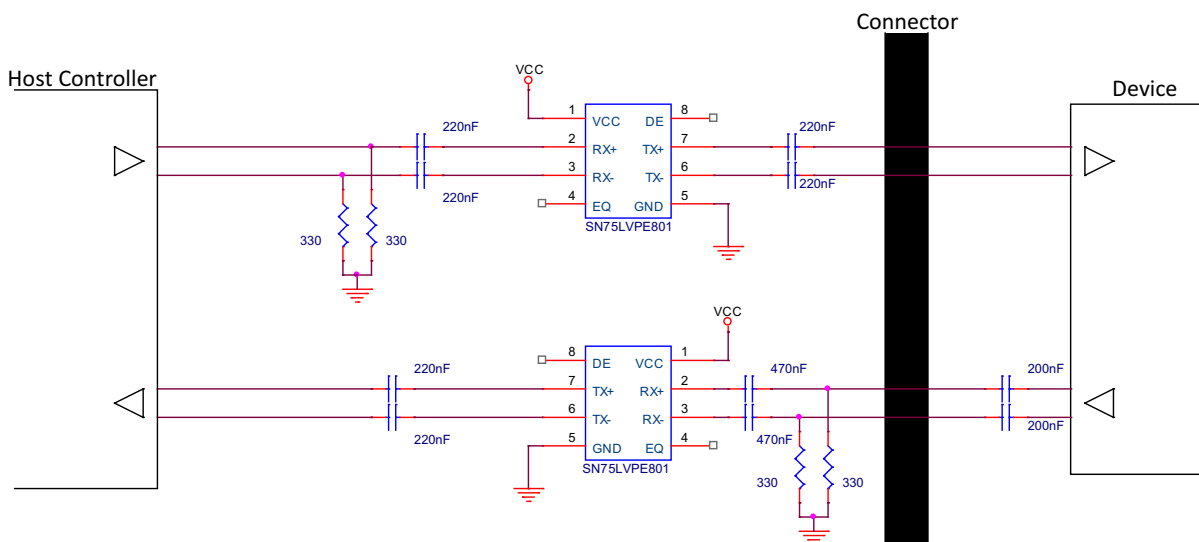


Figure 26. SN75LVPE801 8-Gbps Eye-Diagram

10.2.5 PCIe Applications

PCIe-only applications are implemented in a manner very similar to SATA Express applications as covered in [Detailed Design Procedure](#). Looking at Figure 27, and comparing it to the SATA Express application in Figure 24, a single change is noted. For PCIe applications the 220 nF AC-coupling capacitors on the Host-to-Device link are relocated from the Device side of the connector to the Host side. No other changes are required.



Copyright © 2016, Texas Instruments Incorporated

Figure 27. SN75LVPE801 PCI-Express Reference Schematic
EQ: 7 dB when Floated, DE: 0 dB when Floated

11 Power Supply Recommendations

The SN75LVPE801DRF is designed to operate from a single 3.3-V supply. Always practice proper power-supply sequencing procedure. Apply V_{CC} first before any input signals are applied to the device. The power-down sequence is in reverse order.

12 Layout

12.1 Layout Guidelines

12.1.1 Return Current and Plane References

High frequency return signal/current is defined as the path that a signal follows back to its original source as all signals flow in a closed loop. Minimizing the loop area of the closed loop is beneficial for both EMI (Electro-Magnetic Interference) reduction and signal integrity.

The best way to minimize loop area is to always have a signal reference their nearest solid ground or power plane. Obstructions to the return signal causes signal integrity problems like reflections, crosstalk, undershoot and overshoot.

Signals can reference either power or ground planes, but ground is preferred. Without solid plane references, single ended and differential impedance control is very hard to accomplish; crosstalk to other signals may happen as the return signals have no other path. This type of crosstalk is difficult to troubleshoot.

Symmetric pairing of solid planes in the layer stackup can significantly reduce warping of the PCB during the manufacturing process. Warping of the PCB is crucial to minimize on boards that uses BGA components.

12.1.2 Split Planes – What to Avoid

Never route signals over splits in their perspective reference planes.

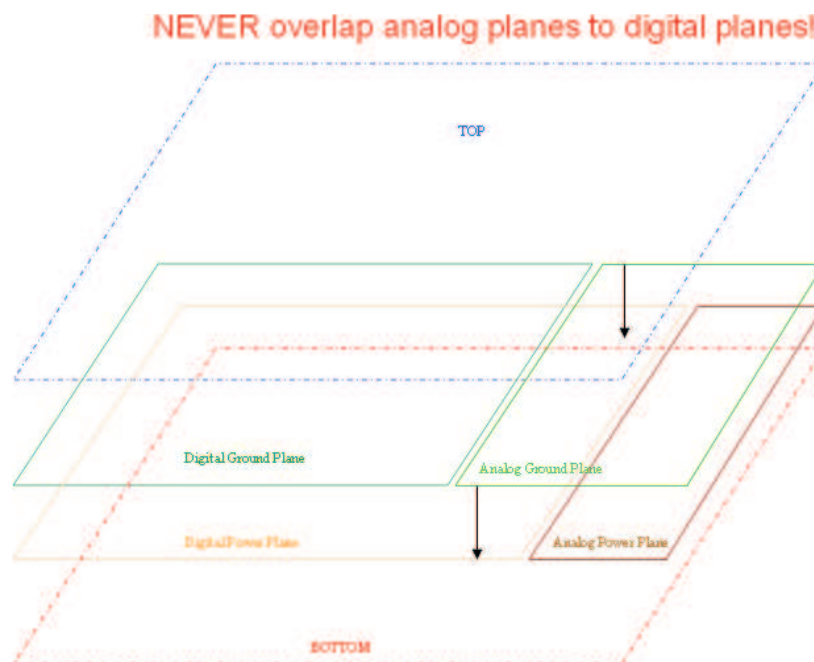


Figure 28. Overlapping Analog and Digital Planes

Layout Guidelines (continued)

This type of routing will compromise signal integrity!!

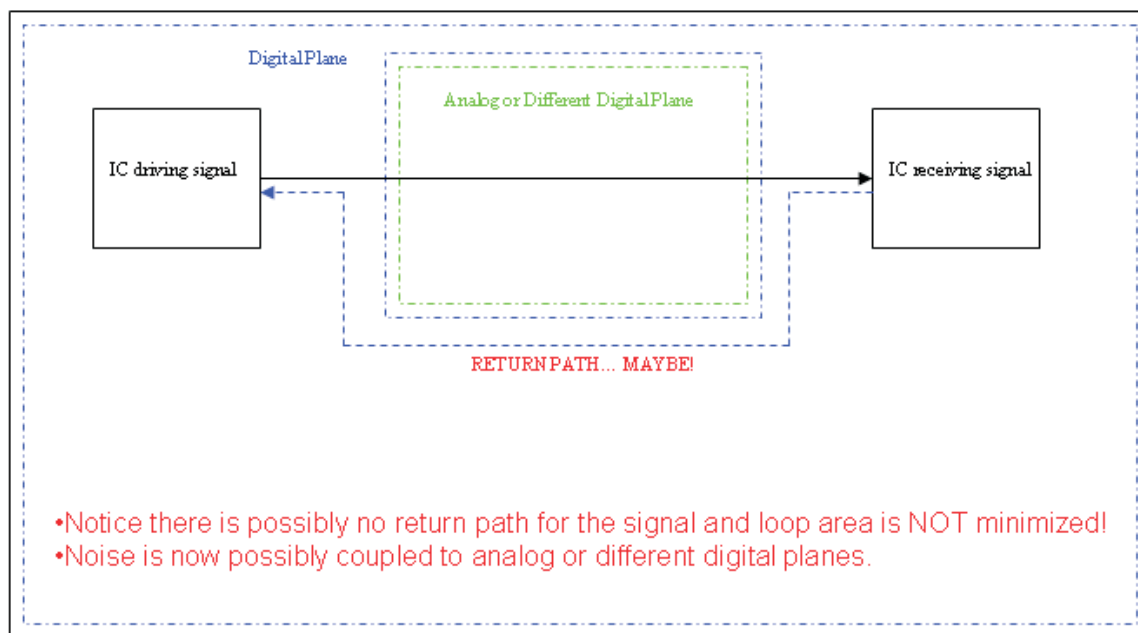


Figure 29. Incorrect Routing

Proper way to route AROUND splits in planes

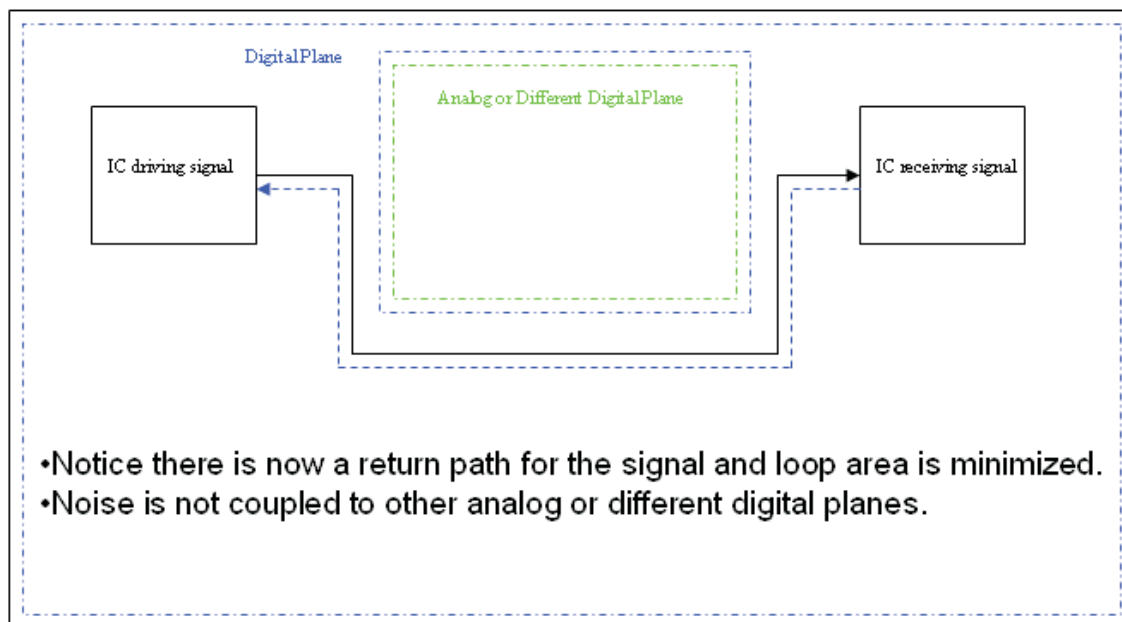


Figure 30. Proper Routing

Layout Guidelines (continued)

12.1.3 Avoiding Crosstalk

Crosstalk is defined as interference from one trace to another by either or both inductive and capacitive coupling. Best ways to avoid crosstalk are:

- Provide stable reference planes for all high speed signals (as noted in previous sections).
- Use the 3W rule (3 times the width of trace for separation) where applicable on all signals, but absolutely use on clock signals.
- Use ground traces/guards around either *victim* or *aggressor* signals prone to crosstalk.
- When space is constrained and limited on areas of the PCB to route parallel buses, series or end termination resistors can be used to route traces closer than what is normally recommended. However, calculations and simulations must be done to validate the use of series or end termination resistors to eliminate crosstalk.



Figure 31. Ways to Avoid Crosstalk

12.2 Layout Example

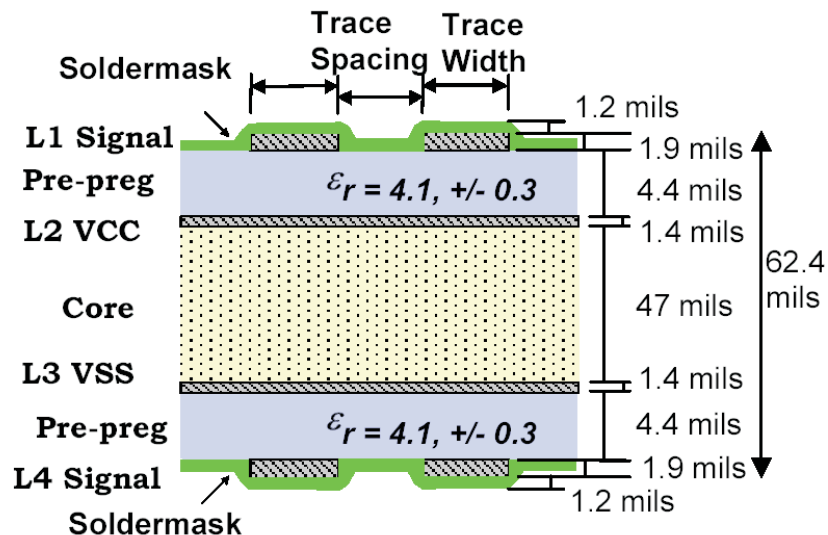


Figure 32. Printed-Circuit Board Stackup (FR-4 Example)

Layout Example (continued)
4 Layer

Layer 1	(Top)
Layer 2	(GND)
Layer 3	(PWR)
Layer 4	(Bottom)

6 Layer

Layer 1	(Top)
Layer 2	(GND)
Layer 3	(Signal)
Layer 4	(Signal)
Layer 5	(PWR)
Layer 6	(Bottom)

10 Layer

Layer 1	(Top)
Layer 2	(GND)
Layer 3	(Signal)
Layer 4	(Signal)
Layer 5	(PWR)
Layer 6	(GND)
Layer 7	(Signal)
Layer 8	(Signal)
Layer 9	(GND)
Layer 10	(Bottom)

PCB layer configuration suggestions for stackup symmetry and signal integrity.

Figure 33. PCB Layer Configuration Suggestions

13 Device and Documentation Support

13.1 Device Support

13.1.1 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

13.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

13.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

13.4 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

13.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

13.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75LVPE801DRFR	ACTIVE	WSO	DRF	8	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	0 to 85	801	Samples
SN75LVPE801DRFT	ACTIVE	WSO	DRF	8	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	0 to 85	801	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75LVPE801DRFR	WSO	DRF	8	3000	180.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2
SN75LVPE801DRFT	WSO	DRF	8	250	180.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2

TAPE AND REEL BOX DIMENSIONS

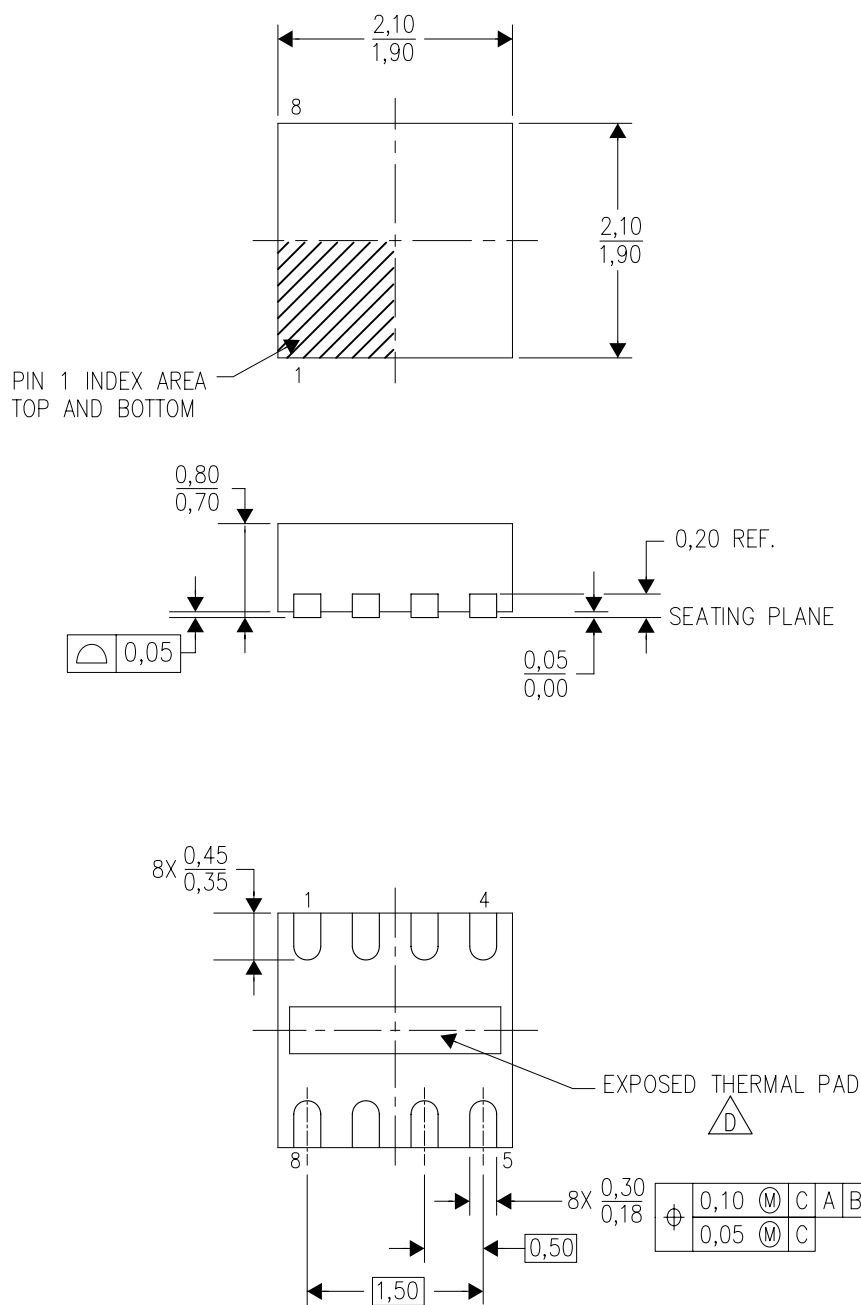


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75LVPE801DRFR	WSN	DRF	8	3000	210.0	185.0	35.0
SN75LVPE801DRFT	WSN	DRF	8	250	210.0	185.0	35.0

DRF (S-PWSON-N8)

PLASTIC SMALL OUTLINE NO-LEAD



4205287/E 10/10

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-Leads (QFN) package configuration.
 - D. The Package thermal pad must be soldered to the board for thermal and mechanical performance. See product data sheet for details regarding the exposed thermal pad dimensions.
 - E. Falls within JEDEC MO-229.

DRF (S-PWSON-N8)

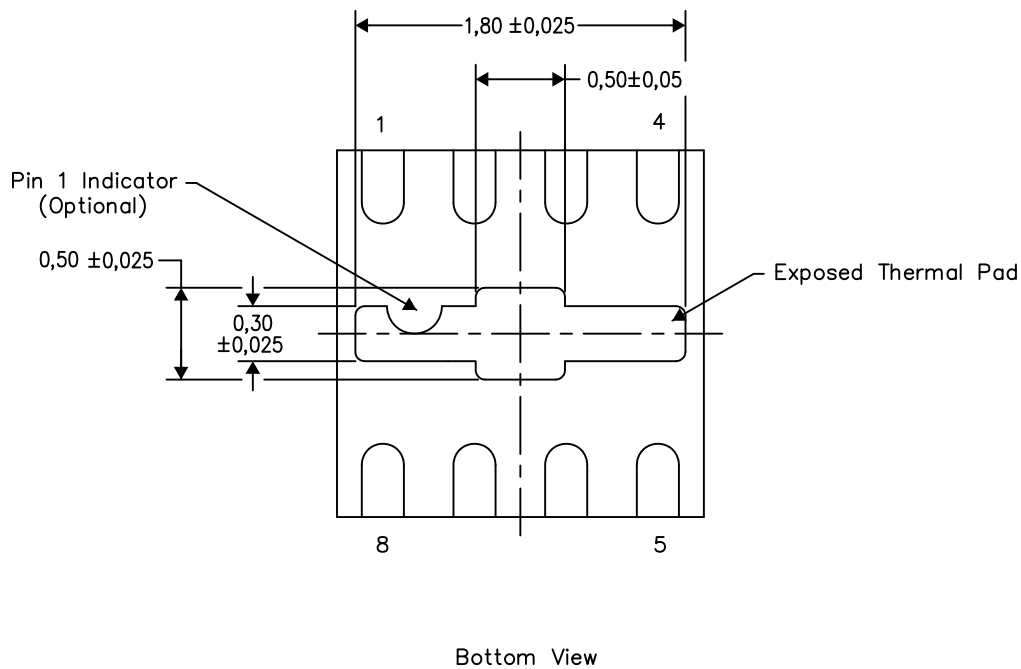
PLASTIC SMALL OUTLINE NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



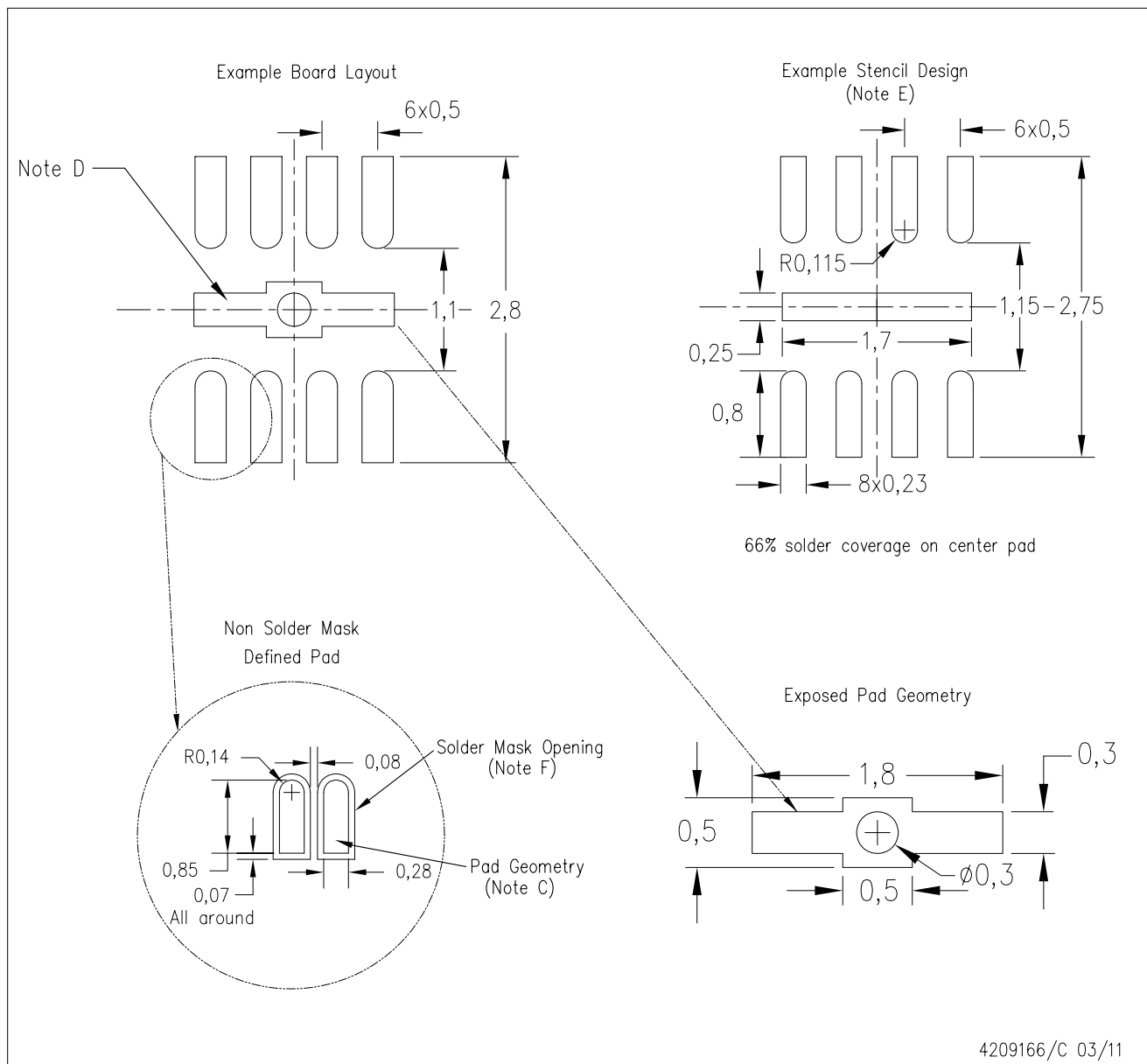
Exposed Thermal Pad Dimensions

4206840/H 12/14

NOTE: A. All linear dimensions are in millimeters

DRF (S-PWSON-N8)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2020, Texas Instruments Incorporated